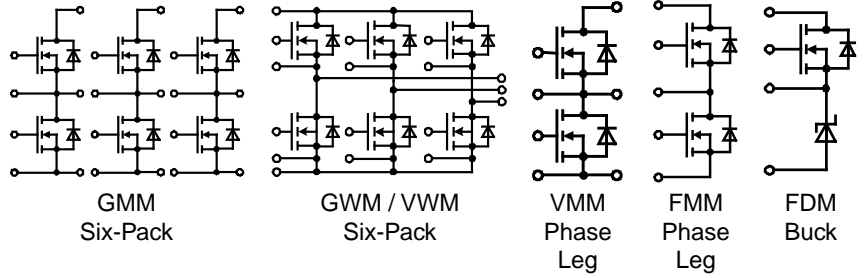


MOSFET Modules

Trench MOSFET Technology

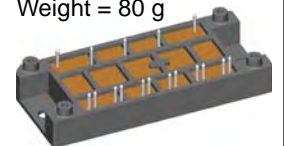
- very low R_{DSon}
- fast body diode



Part Type	V_{DSS}	I_{D25} $T_C = 25^\circ C$	I_{D90} $T_C = 90^\circ C$	R_{DSon} typ. $T_J = 25^\circ C$	t_r	t_f	R_{thJC}	Fig. No.	Package style Outline drawings on pages O-30...O-52	
➤ New	V	A	A	mΩ	ns	ns	K/W			
Phase Leg Configuration										
FMM 150-0075P	75	150	120	4.7	60	60	0.60	X024a	X024a ISOPLUS i4-PAC™ Weight = 6 g	
VMM 1500-0075P	75	1500	1200 / 80°C	0.55	200	170	0.06	X130a		
FMM 75-01F	100	75	50	18	60	60	0.50	X024a		
VMM 1000-01P	100	1000	800 / 80°C	0.75	100	100	0.06	X130a		
FMM 65-015P	150	65	50	13	100	80	0.60	X024a		
ISOPLUS-DIL™										
Six-Pack Configuration										
VWM 350-0075P	75	340	250 / 80°C	2.3	contact factory		0.26	X104		
VWM 200-01P	100	210	170 / 80°C	3.6	contact factory		0.26	X104		
GWM 220-004P3-SL	40	190	145	2.0	85	90	0.90	X026a		
GWM 220-004P3-SMD		190	145	2.0	85	90	0.90	X026c		
➤ GWM 220-004X1-SL	under development								X026a	
➤ GWM 220-004X1-SMD	under development								X026c	
➤ GWM 160-0055X1-SL	55	160	120	2.7	125 *	120 *	0.90	X026a	X026c ISOPLUS-DIL™ Weight = 25 g	
➤ GWM 160-0055X1-SMD		160	120	2.7	125 *	120 *	0.90	X026c		
➤ GWM 120-0075X1-SL	75	under development							X026a	
➤ GWM 120-0075X1-SMD		under development							X026c	
➤ GWM 100-0085X1-SMD	85	contact factory							X026c	
➤ GWM 100-01X1-SL	100	90	68	7.5	95 *	55 *	0.90	X026a		
➤ GWM 100-01X1-SMD		90	68	7.5	95 *	55 *	0.90	X026c		
* inductive load										
➤ GMM 3x160-0055X2-SMD	55	under development							X026d	X026d ISOPLUS-DIL™ Weight = 25 g
➤ GMM 3x120-0075X2-SMD	75	under development							X026d	
Buck Configuration										
FDM 100-0045SP Mosfet/Diode	55 / 45	100 / 110	80 / 80	5.7 **	115 **	155 **	1.00	X024a		

** only MOSFET data

X104 **V2-Pack**
Weight = 80 g



X130a **Y3**
Weight = 250 g

